## **High Power GaAs FETs (L, S-Band)**

#### **Features**

- High power
  - $P_{1dB} = 42.0 \text{ dBm at } 1.8 \text{ GHz}$
- High gain
- G<sub>1dB</sub> = 14.0 dB at 1.8 GHz
  Partially matched type
- Hermetically sealed package

### RF Performance Specifications ( $T_a = 25^{\circ}$ C)

Characteristics	Symbol	Condition	Unit	Min.	Тур.	Max
Output Power at 1dB Compression Point	P <sub>1dB</sub>		dBm	41.0	42.0	-
Power Gain at 1dB Compression Point	G <sub>1dB</sub>	V <sub>DS</sub> = 10V f = 1.8 GHz	dB	13.0	14.0	_
Drain Current	I <sub>DS</sub>		А	_	4.0	5.0
Power Added Efficiency	N <sub>add</sub>		%	_	38	_
Channel-Temperature Rise	$\Delta T_{ch}$	NOTE 1	°C	_	_	80

## Electrical Characteristics (T<sub>a</sub> = 25° C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max
Trans-conductance	gm	V <sub>DS</sub> =3V I <sub>DS</sub> =3.5A	mS	_	3200	-
Pinch-off Voltage	V <sub>GSoff</sub>	V <sub>DS</sub> =3V I <sub>DS</sub> =70mA	V	-1.0	-3.0	-4.0
Saturated Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =3V V <sub>GS</sub> =0V	А	_	10	13
Gate to Source Breakdown Voltage	V <sub>GSO</sub>	I <sub>GS</sub> =-210 μA	V	-5	_	_
Thermal Resistance	R <sub>th (c-c)</sub>	Channel to case	°C/W	_	1.9	2.5

NOTE 1: $\Delta$ Tch = (V<sub>DS</sub> x I<sub>DS</sub> + Pin - P<sub>1dB</sub>) x R<sub>th(c-c)</sub>

The information contained here is subject to change without notice.

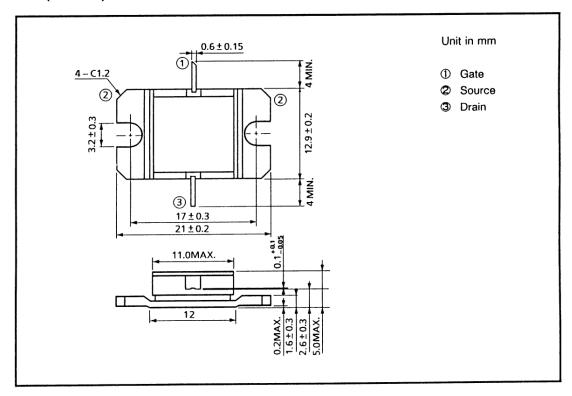
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# Absolute Maximum Ratings ( $T_a = 25^{\circ} C$ )

Characteristic	Symbol	Unit	Rating
Drain Source Voltage	V <sub>DS</sub>	V	15
Gate Source Voltage	V <sub>GS</sub>	V	-5
Drain Current	I <sub>D</sub>	А	10
Total Power Dissipation (Tc = 25°C)	P <sub>T</sub>	W	60
Channel Temperature	T <sub>ch</sub>	°C	175
Storage Temperature	T <sub>stg</sub>	°C	-65~175

### Package Outline (2-11D1B)

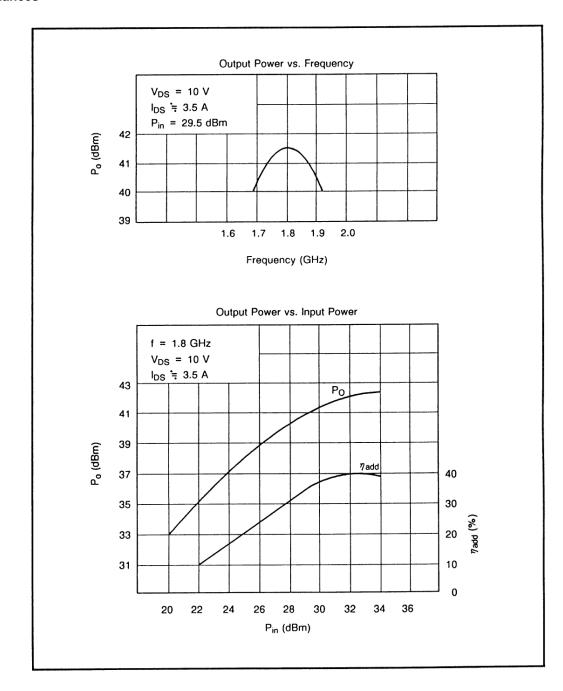


## **Handling Precautions for Packaged Type**

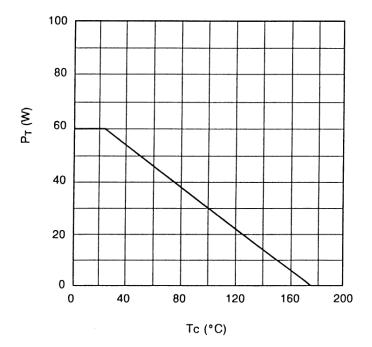
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

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### **RF Performances**



# **Power Dissipation vs. Case Temperature**



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